



Welcome to [E-XFL.COM](#)

#### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

#### Applications of "[Embedded - Microcontrollers](#)"

##### Details

Product Status	Obsolete
Core Processor	RL78
Core Size	16-Bit
Speed	32MHz
Connectivity	CSI, I <sup>2</sup> C, LINbus, UART/USART
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	21
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	1.6V ~ 5.5V
Data Converters	A/D 8x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	30-LSSOP (0.240", 6.10mm Width)
Supplier Device Package	30-LSSOP
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f101agasp-v0">https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f101agasp-v0</a>

## O ROM, RAM capacities

Flash ROM	Data flash	RAM	RL78/G13					
			20 pins	24 pins	25 pins	30 pins	32 pins	36 pins
128 KB	8 KB	12 KB	—	—	—	R5F100AG	R5F100BG	R5F100CG
	—		—	—	—	R5F101AG	R5F101BG	R5F101CG
96 KB	8 KB	8 KB	—	—	—	R5F100AF	R5F100BF	R5F100CF
	—		—	—	—	R5F101AF	R5F101BF	R5F101CF
64 KB	4 KB	4 KB Note	R5F1006E	R5F1007E	R5F1008E	R5F100AE	R5F100BE	R5F100CE
	—		R5F1016E	R5F1017E	R5F1018E	R5F101AE	R5F101BE	R5F101CE
48 KB	4 KB	3 KB Note	R5F1006D	R5F1007D	R5F1008D	R5F100AD	R5F100BD	R5F100CD
	—		R5F1016D	R5F1017D	R5F1018D	R5F101AD	R5F101BD	R5F101CD
32 KB	4 KB	2 KB	R5F1006C	R5F1007C	R5F1008C	R5F100AC	R5F100BC	R5F100CC
	—		R5F1016C	R5F1017C	R5F1018C	R5F101AC	R5F101BC	R5F101CC
16 KB	4 KB	2 KB	R5F1006A	R5F1007A	R5F1008A	R5F100AA	R5F100BA	R5F100CA
	—		R5F1016A	R5F1017A	R5F1018A	R5F101AA	R5F101BA	R5F101CA

Flash ROM	Data flash	RAM	RL78/G13							
			40 pins	44 pins	48 pins	52 pins	64 pins	80 pins	100 pins	128 pins
512 KB	8 KB	32 KB Note	—	R5F100FL	R5F100GL	R5F100JL	R5F100LL	R5F100ML	R5F100PL	R5F100SL
	—		—	R5F101FL	R5F101GL	R5F101JL	R5F101LL	R5F101ML	R5F101PL	R5F101SL
384 KB	8 KB	24 KB	—	R5F100FK	R5F100GK	R5F100JK	R5F100LK	R5F100MK	R5F100PK	R5F100SK
	—		—	R5F101FK	R5F101GK	R5F101JK	R5F101LK	R5F101MK	R5F101PK	R5F101SK
256 KB	8 KB	20 KB Note	—	R5F100FJ	R5F100GJ	R5F100JJ	R5F100LJ	R5F100MJ	R5F100PJ	R5F100SJ
	—		—	R5F101FJ	R5F101GJ	R5F101JJ	R5F101LJ	R5F101MJ	R5F101PJ	R5F101SJ
192 KB	8 KB	16 KB	R5F100EH	R5F100FH	R5F100GH	R5F100JH	R5F100LH	R5F100MH	R5F100PH	R5F100SH
	—		R5F101EH	R5F101FH	R5F101GH	R5F101JH	R5F101LH	R5F101MH	R5F101PH	R5F101SH
128 KB	8 KB	12 KB	R5F100EG	R5F100FG	R5F100GG	R5F100JG	R5F100LG	R5F100MG	R5F100PG	—
	—		R5F101EG	R5F101FG	R5F101GG	R5F101JG	R5F101LG	R5F101MG	R5F101PG	—
96 KB	8 KB	8 KB	R5F100EF	R5F100FF	R5F100GF	R5F100JF	R5F100LF	R5F100MF	R5F100PF	—
	—		R5F101EF	R5F101FF	R5F101GF	R5F101JF	R5F101LF	R5F101MF	R5F101PF	—
64 KB	4 KB	4 KB Note	R5F100EE	R5F100FE	R5F100GE	R5F100JE	R5F100LE	—	—	—
	—		R5F101EE	R5F101FE	R5F101GE	R5F101JE	R5F101LE	—	—	—
48 KB	4 KB	3 KB Note	R5F100ED	R5F100FD	R5F100GD	R5F100JD	R5F100LD	—	—	—
	—		R5F101ED	R5F101FD	R5F101GD	R5F101JD	R5F101LD	—	—	—
32 KB	4 KB	2 KB	R5F100EC	R5F100FC	R5F100GC	R5F100JC	R5F100LC	—	—	—
	—		R5F101EC	R5F101FC	R5F101GC	R5F101JC	R5F101LC	—	—	—
16 KB	4 KB	2 KB	R5F100EA	R5F100FA	R5F100GA	—	—	—	—	—
	—		R5F101EA	R5F101FA	R5F101GA	—	—	—	—	—

**Note** The flash library uses RAM in self-programming and rewriting of the data flash memory.

The target products and start address of the RAM areas used by the flash library are shown below.

R5F100xD, R5F101xD (x = 6 to 8, A to C, E to G, J, L): Start address FF300H

R5F100xE, R5F101xE (x = 6 to 8, A to C, E to G, J, L): Start address FEF00H

R5F100xJ, R5F101xJ (x = F, G, J, L, M, P): Start address FAF00H

R5F100xL, R5F101xL (x = F, G, J, L, M, P, S): Start address F7F00H

For the RAM areas used by the flash library, see **Self RAM list of Flash Self-Programming Library for RL78 Family (R20UT2944)**.

**Table 1-1. List of Ordering Part Numbers**

(5/12)

Pin count	Package	Data flash	Fields of Application <small>Note</small>	Ordering Part Number
48 pins	48-pin plastic LFQFP (7 × 7 mm, 0.5 mm pitch)	Mounted	A D G	R5F100GAAFB#V0, R5F100GCAFB#V0, R5F100GDAFB#V0, R5F100GEAFB#V0, R5F100GFAFB#V0, R5F100GGAFB#V0, R5F100GHAFB#V0, R5F100GJAFB#V0, R5F100GKAFB#V0, R5F100GLAFB#V0 R5F100GAAFB#X0, R5F100GCAFB#X0, R5F100GDAFB#X0, R5F100GEAFB#X0, R5F100GFAFB#X0, R5F100GGAFB#X0, R5F100GHAFB#X0, R5F100GJAFB#X0, R5F100GKAFB#X0, R5F100GLAFB#X0 R5F100GADFB#V0, R5F100GCDFB#V0, R5F100GDDFB#V0, R5F100GEDFB#V0, R5F100GFDFB#V0, R5F100GGDFB#V0, R5F100GHDFB#V0, R5F100GJDFB#V0, R5F100GKDFB#V0, R5F100GLDFB#V0 R5F100GADFB#X0, R5F100GCDFB#X0, R5F100GDDFB#X0, R5F100GEDFB#X0, R5F100GFDFB#X0, R5F100GGDFB#X0, R5F100GHDFB#X0, R5F100GJDFB#X0, R5F100GKDFB#X0, R5F100GLDFB#X0 R5F100GAGFB#V0, R5F100GCGFB#V0, R5F100GDGFB#V0, R5F100GEGFB#V0, R5F100GFGFB#V0, R5F100GGGFB#V0, R5F100GHGFB#V0, R5F100GJGFB#V0 R5F100GAGFB#X0, R5F100GCGFB#X0, R5F100GDGFB#X0, R5F100GEGFB#X0, R5F100GFGFB#X0, R5F100GGGFB#X0, R5F100GHGFB#X0, R5F100GJGFB#X0
		Not mounted	A D	R5F101GAAFB#V0, R5F101GCAFB#V0, R5F101GDAFB#V0, R5F101GEAFB#V0, R5F101GFAFB#V0, R5F101GGAFB#V0, R5F101GHAFB#V0, R5F101GJAFB#V0, R5F101GKAFB#V0, R5F101GLAFB#V0 R5F101GAAFB#X0, R5F101GCAFB#X0, R5F101GDAFB#X0, R5F101GEAFB#X0, R5F101GFAFB#X0, R5F101GGAFB#X0, R5F101GHAFB#X0, R5F101GJAFB#X0, R5F101GKAFB#X0, R5F101GLAFB#X0 R5F101GADFB#V0, R5F101GCDFB#V0, R5F101GDDFB#V0, R5F101GEDFB#V0, R5F101GFDFB#V0, R5F101GGDFB#V0, R5F101GHDFB#V0, R5F101GJDFB#V0, R5F101GKDFB#V0, R5F101GLDFB#V0 R5F101GADFB#X0, R5F101GCDFB#X0, R5F101GDDFB#X0, R5F101GEDFB#X0, R5F101GFDFB#X0, R5F101GGDFB#X0, R5F101GHDFB#X0, R5F101GJDFB#X0, R5F101GKDFB#X0, R5F101GLDFB#X0

**Note** For the fields of application, refer to **Figure 1-1 Part Number, Memory Size, and Package of RL78/G13**.

**Caution** The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.

Table 1-1. List of Ordering Part Numbers

(6/12)

Pin count	Package	Data flash	Fields of Application <small>Note</small>	Ordering Part Number
48 pins	48-pin plastic HWQFN (7 × 7 mm, 0.5 mm pitch)	Mounted	A D G	R5F100GAANA#U0, R5F100GCANA#U0, R5F100GDANA#U0, R5F100GEANA#U0, R5F100GFANA#U0, R5F100GGANA#U0, R5F100GHANA#U0, R5F100GJANA#U0, R5F100GKANA#U0, R5F100GLANA#U0 R5F100GAANA#W0, R5F100GCANA#W0, R5F100GDANA#W0, R5F100GEANA#W0, R5F100GFANA#W0, R5F100GGANA#W0, R5F100GHANA#W0, R5F100GJANA#W0, R5F100GKANA#W0, R5F100GLANA#W0 R5F100GADNA#U0, R5F100GCDNA#U0, R5F100GDDNA#U0, R5F100GEDNA#U0, R5F100GFDNA#U0, R5F100GGDNA#U0, R5F100GHDNA#U0, R5F100GJDNA#U0, R5F100GKDNA#U0, R5F100GLDNA#U0 R5F100GADNA#W0, R5F100GCDNA#W0, R5F100GDDNA#W0, R5F100GEDNA#W0, R5F100GFDNA#W0, R5F100GGDNA#W0, R5F100GHDNA#W0, R5F100GJDNA#W0, R5F100GKDNA#W0, R5F100GLDNA#W0 R5F100GAGNA#U0, R5F100GCGNA#U0, R5F100GDGNA#U0, R5F100GEGNA#U0, R5F100GFGNA#U0, R5F100GGGNA#U0, R5F100GHGNA#U0, R5F100GJGNA#U0 R5F100GAGNA#W0, R5F100GCGNA#W0, R5F100GDGNA#W0, R5F100GEGNA#W0, R5F100GFGNA#W0, R5F100GGGNA#W0, R5F100GHGNA#W0, R5F100GJGNA#W0
	Not mounted	A D		R5F101GAANA#U0, R5F101GCANA#U0, R5F101GDANA#U0, R5F101GEANA#U0, R5F101GFANA#U0, R5F101GGANA#U0, R5F101GHANA#U0, R5F101GJANA#U0, R5F101GKANA#U0, R5F101GLANA#U0 R5F101GAANA#W0, R5F101GCANA#W0, R5F101GDANA#W0, R5F101GEANA#W0, R5F101GFANA#W0, R5F101GGANA#W0, R5F101GHANA#W0, R5F101GJANA#W0, R5F101GKANA#W0, R5F101GLANA#W0 R5F101GADNA#U0, R5F101GCDNA#U0, R5F101GDDNA#U0, R5F101GEDNA#U0, R5F101GFDNA#U0, R5F101GGDNA#U0, R5F101GHDNA#U0, R5F101GJDNA#U0, R5F101GKDNA#U0, R5F101GLDNA#U0 R5F101GADNA#W0, R5F101GCDNA#W0, R5F101GDDNA#W0, R5F101GEDNA#W0, R5F101GFDNA#W0, R5F101GGDNA#W0, R5F101GHDNA#W0, R5F101GJDNA#W0, R5F101GKDNA#W0, R5F101GLDNA#W0

**Note** For the fields of application, refer to **Figure 1-1 Part Number, Memory Size, and Package of RL78/G13**.

**Caution** The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.

Table 1-1. List of Ordering Part Numbers

(11/12)

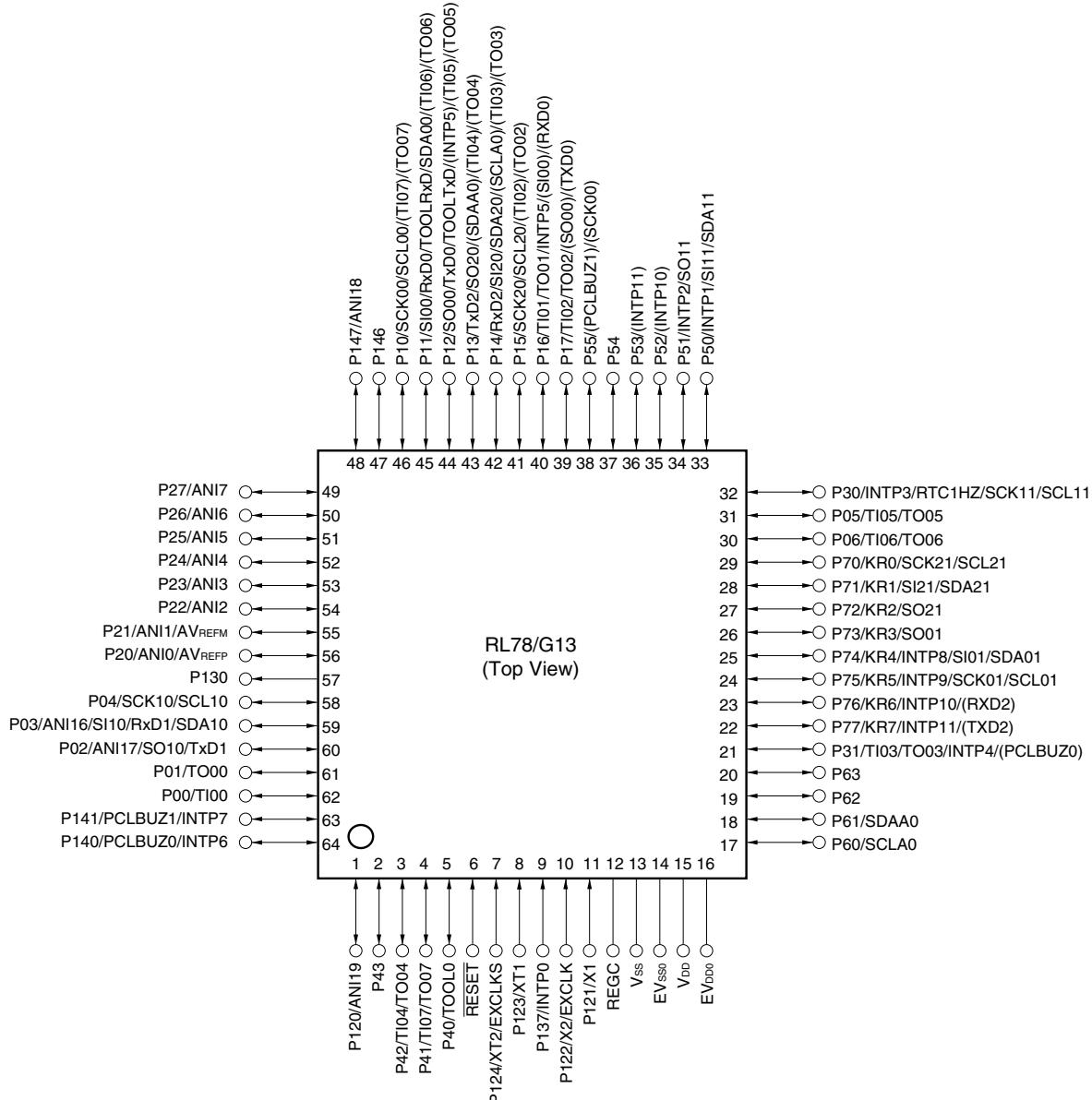
Pin count	Package	Data flash	Fields of Application <small>Note</small>	Ordering Part Number
100 pins	100-pin plastic LFQFP (14 × 14 mm, 0.5 mm pitch)	Mounted	A	R5F100PFAFB#V0, R5F100PGAFB#V0, R5F100PHAFB#V0, R5F100PJAFB#V0, R5F100PKAFB#V0, R5F100PLAFB#V0
			D	R5F100PFAFB#X0, R5F100PGAFB#X0, R5F100PHAFB#X0, R5F100PJAFB#X0, R5F100PKAFB#X0, R5F100PLAFB#X0
			G	R5F100PFDFB#V0, R5F100PGDFB#V0, R5F100PHDFB#V0, R5F100PJDFB#V0, R5F100PKDFB#V0, R5F100PLDFB#V0
			A	R5F100PFDFB#X0, R5F100PGDFB#X0, R5F100PHDFB#X0, R5F100PJDFB#X0, R5F100PKDFB#X0, R5F100PLDFB#X0
	100-pin plastic LQFP (14 × 20 mm, 0.65 mm pitch)	Not mounted	A	R5F101PFAFB#V0, R5F101PGAFB#V0, R5F101PHAFB#V0, R5F101PJAFB#V0, R5F101PKAFB#V0, R5F101PLAFB#V0
			D	R5F101PFAFB#X0, R5F101PGAFB#X0, R5F101PHAFB#X0, R5F101PJAFB#X0, R5F101PKAFB#X0, R5F101PLAFB#X0
			A	R5F101PFDFB#V0, R5F101PGDFB#V0, R5F101PHDFB#V0, R5F101PJDFB#V0, R5F101PKDFB#V0, R5F101PLDFB#V0
			D	R5F101PFDFB#X0, R5F101PGDFB#X0, R5F101PHDFB#X0, R5F101PJDFB#X0, R5F101PKDFB#X0, R5F101PLDFB#X0
		Mounted	A	R5F100PFAFA#V0, R5F100PGAFA#V0, R5F100PHAFKA#V0, R5F100PJAFKA#V0, R5F100PKAFKA#V0, R5F100PLAFKA#V0
		D	R5F100PFAFA#X0, R5F100PGAFA#X0, R5F100PHAFKA#X0, R5F100PJAFKA#X0, R5F100PKAFKA#X0, R5F100PLAFKA#X0	
		G	R5F100PF DFA#V0, R5F100PG DFA#V0, R5F100PH DFA#V0, R5F100PJ DFA#V0, R5F100PK DFA#V0, R5F100PL DFA#V0	
		A	R5F100PF DFA#X0, R5F100PG DFA#X0, R5F100PH DFA#X0, R5F100PJ DFA#X0, R5F100PK DFA#X0, R5F100PL DFA#X0	
		Not mounted	A	R5F101PFAFA#V0, R5F101PGAFA#V0, R5F101PHAFKA#V0, R5F101PJAFKA#V0, R5F101PKAFKA#V0, R5F101PLAFKA#V0
		D	R5F101PFAFA#X0, R5F101PGAFA#X0, R5F101PHAFKA#X0, R5F101PJAFKA#X0, R5F101PKAFKA#X0, R5F101PLAFKA#X0	

**Note** For the fields of application, refer to **Figure 1-1 Part Number, Memory Size, and Package of RL78/G13**.

**Caution** The ordering part numbers represent the numbers at the time of publication. For the latest ordering part numbers, refer to the target product page of the Renesas Electronics website.

### 1.3.11 64-pin products

- 64-pin plastic LQFP (12 × 12 mm, 0.65 mm pitch)
- 64-pin plastic LFQFP (10 × 10 mm, 0.5 mm pitch)



**Cautions** 1. Make EV<sub>SS0</sub> pin the same potential as V<sub>ss</sub> pin.

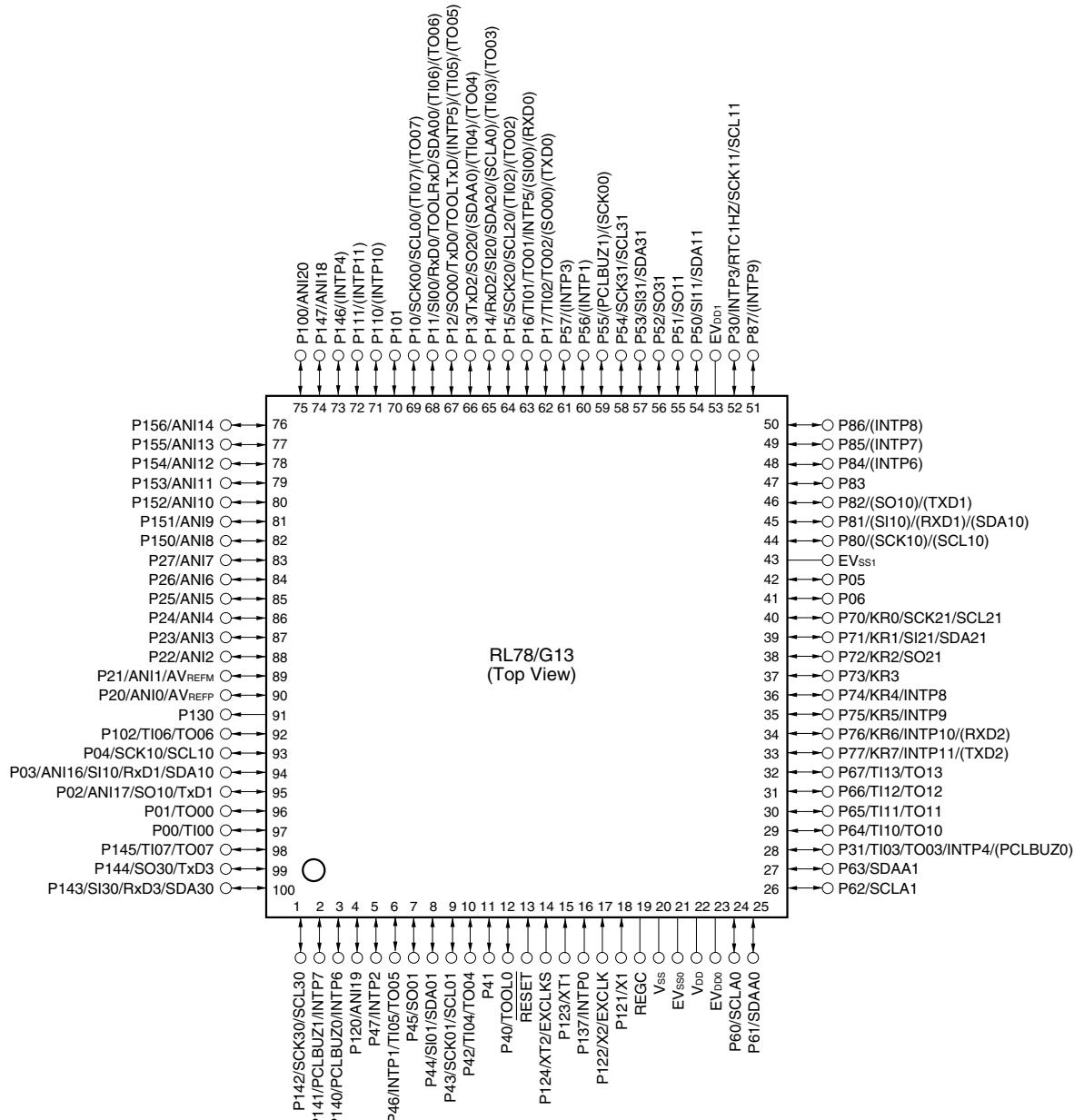
2. Make V<sub>DD</sub> pin the potential that is higher than EV<sub>VDD0</sub> pin.
3. Connect the REGC pin to V<sub>ss</sub> via a capacitor (0.47 to 1  $\mu$ F).

**Remarks** 1. For pin identification, see **1.4 Pin Identification**.

2. When using the microcontroller for an application where the noise generated inside the microcontroller must be reduced, it is recommended to supply separate powers to the V<sub>DD</sub> and EV<sub>VDD0</sub> pins and connect the V<sub>ss</sub> and EV<sub>SS0</sub> pins to separate ground lines.
3. Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.

### 1.3.13 100-pin products

- 100-pin plastic LQFP (14 × 14 mm, 0.5 mm pitch)

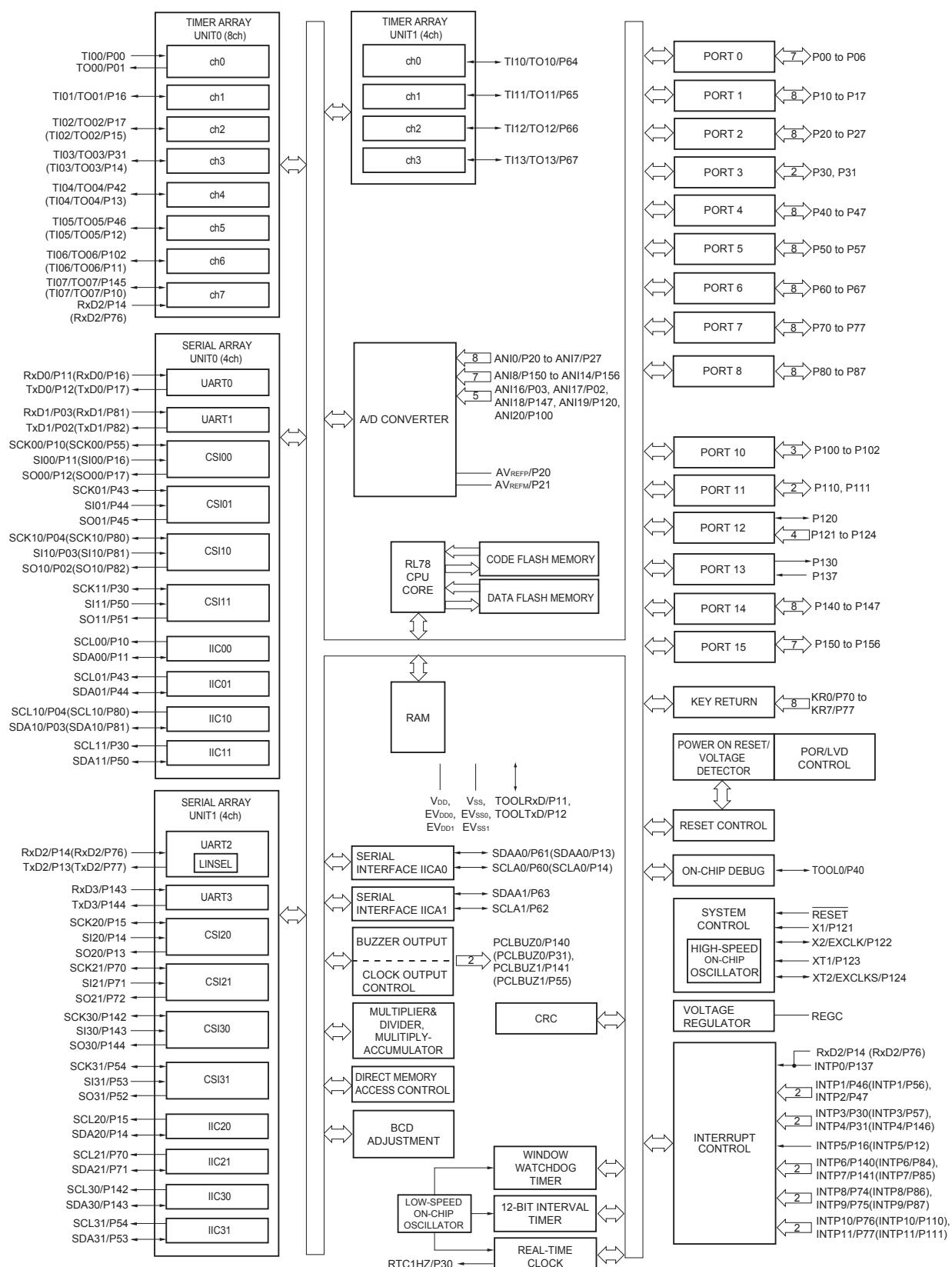


2. Make V<sub>dd</sub> pin the potential that is higher than EV<sub>dd0</sub>, EV<sub>dd1</sub> pins (EV<sub>dd0</sub> = EV<sub>dd1</sub>).
3. Connect the REGC pin to V<sub>ss</sub> via a capacitor (0.47 to 1  $\mu$ F).

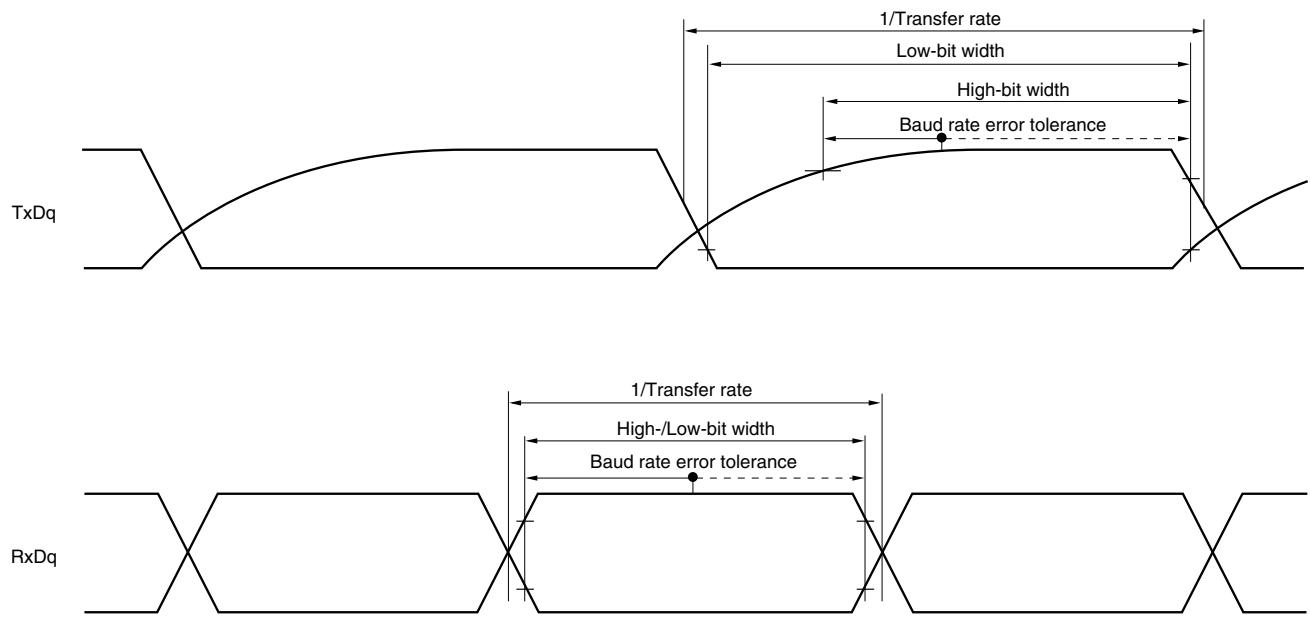
**Remarks** 1. For pin identification, see 1.4 Pin Identification.

2. When using the microcontroller for an application where the noise generated inside the microcontroller must be reduced, it is recommended to supply separate powers to the V<sub>dd</sub>, EV<sub>dd0</sub> and EV<sub>dd1</sub> pins and connect the V<sub>ss</sub>, EV<sub>ss0</sub> and EV<sub>ss1</sub> pins to separate ground lines.
3. Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.

### 1.5.13 100-pin products



**Remark** Functions in parentheses in the above figure can be assigned via settings in the peripheral I/O redirection register (PIOR). Refer to **Figure 4-8 Format of Peripheral I/O Redirection Register (PIOR)** in the RL78/G13 User's Manual.

**UART mode bit width (during communication at different potential) (reference)**

- Remarks**
1.  $R_b[\Omega]$ : Communication line (TxDq) pull-up resistance,  
 $C_b[F]$ : Communication line (TxDq) load capacitance,  $V_b[V]$ : Communication line voltage
  2. q: UART number (q = 0 to 3), g: PIM and POM number (g = 0, 1, 8, 14)
  3.  $f_{MCK}$ : Serial array unit operation clock frequency  
 (Operation clock to be set by the CKSmn bit of serial mode register mn (SMRmn).  
 m: Unit number, n: Channel number (mn = 00 to 03, 10 to 13))
  4. UART2 cannot communicate at different potential when bit 1 (PIOR1) of peripheral I/O redirection register (PIOR) is 1.

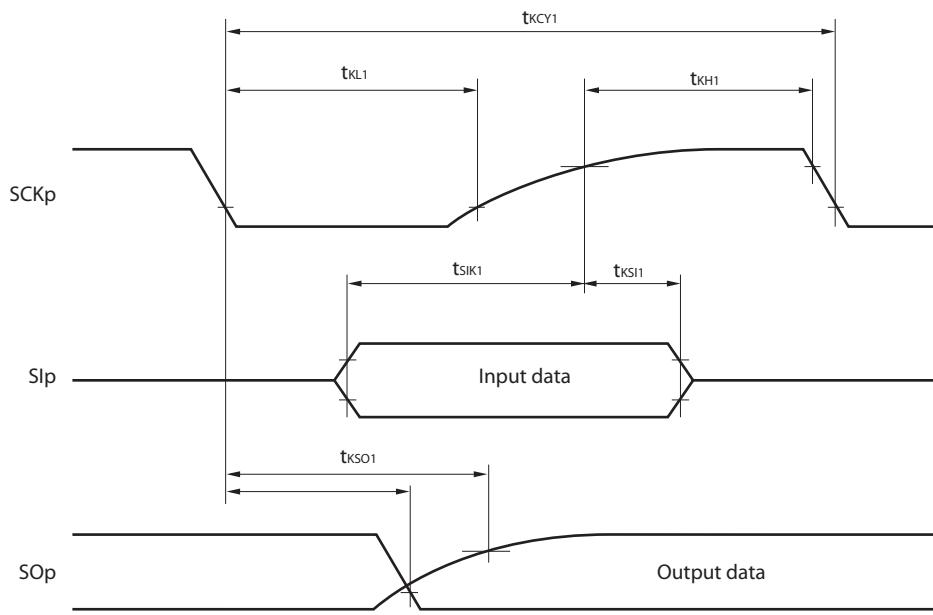
(7) Communication at different potential (2.5 V, 3 V) (CSI mode) (master mode, SCKp... internal clock output, corresponding CSI00 only) (1/2)

( $T_A = -40$  to  $+85^\circ\text{C}$ ,  $2.7 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$ ,  $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$ )

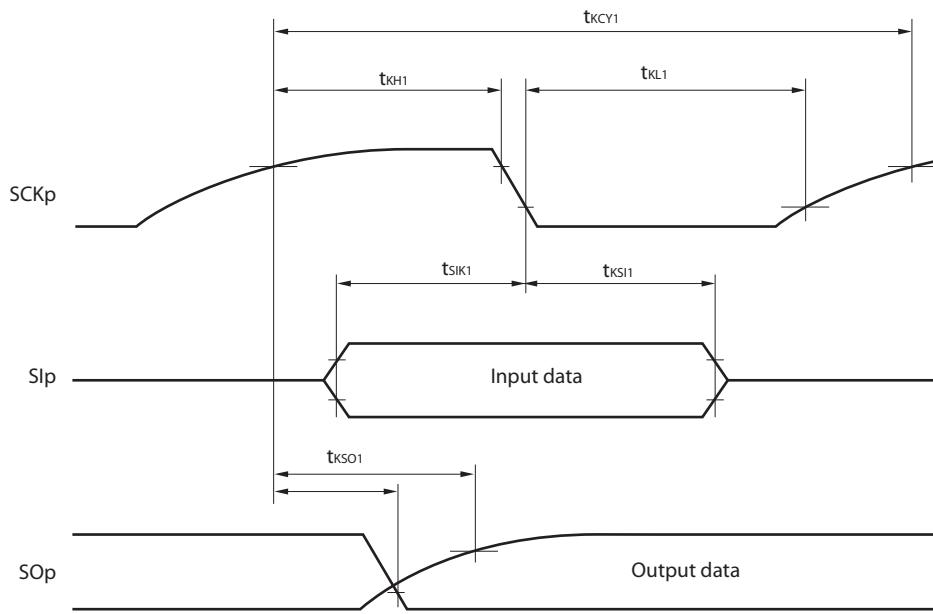
Parameter	Symbol	Conditions		HS (high-speed main) Mode		LS (low-speed main) Mode		LV (low-voltage main) Mode		Unit
				MIN.	MAX.	MIN.	MAX.	MIN.	MAX.	
SCKp cycle time	t <sub>KCY1</sub>	t <sub>KCY1</sub> ≥ 2/f <sub>CLK</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V, C <sub>b</sub> = 20 pF, R <sub>b</sub> = 1.4 kΩ	200		1150		1150		ns
			2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V, C <sub>b</sub> = 20 pF, R <sub>b</sub> = 2.7 kΩ	300		1150		1150		ns
SCKp high-level width	t <sub>KH1</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V, C <sub>b</sub> = 20 pF, R <sub>b</sub> = 1.4 kΩ	t <sub>KCY1</sub> /2 – 50		t <sub>KCY1</sub> /2 – 50		t <sub>KCY1</sub> /2 – 50			ns
		2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V, C <sub>b</sub> = 20 pF, R <sub>b</sub> = 2.7 kΩ	t <sub>KCY1</sub> /2 – 120		t <sub>KCY1</sub> /2 – 120		t <sub>KCY1</sub> /2 – 120			ns
SCKp low-level width	t <sub>KL1</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V, C <sub>b</sub> = 20 pF, R <sub>b</sub> = 1.4 kΩ	t <sub>KCY1</sub> /2 – 7		t <sub>KCY1</sub> /2 – 50		t <sub>KCY1</sub> /2 – 50			ns
		2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V, C <sub>b</sub> = 20 pF, R <sub>b</sub> = 2.7 kΩ	t <sub>KCY1</sub> /2 – 10		t <sub>KCY1</sub> /2 – 50		t <sub>KCY1</sub> /2 – 50			ns
Slp setup time (to SCKp↑) <sup>Note 1</sup>	t <sub>SIK1</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V, C <sub>b</sub> = 20 pF, R <sub>b</sub> = 1.4 kΩ	58		479		479			ns
		2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V, C <sub>b</sub> = 20 pF, R <sub>b</sub> = 2.7 kΩ	121		479		479			ns
Slp hold time (from SCKp↑) <sup>Note 1</sup>	t <sub>KS1</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V, C <sub>b</sub> = 20 pF, R <sub>b</sub> = 1.4 kΩ	10		10		10			ns
		2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V, C <sub>b</sub> = 20 pF, R <sub>b</sub> = 2.7 kΩ	10		10		10			ns
Delay time from SCKp↓ to SO <sub>p</sub> output <sup>Note 1</sup>	t <sub>KS01</sub>	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, 2.7 V ≤ V <sub>b</sub> ≤ 4.0 V, C <sub>b</sub> = 20 pF, R <sub>b</sub> = 1.4 kΩ		60		60		60		ns
		2.7 V ≤ EV <sub>DD0</sub> < 4.0 V, 2.3 V ≤ V <sub>b</sub> ≤ 2.7 V, C <sub>b</sub> = 20 pF, R <sub>b</sub> = 2.7 kΩ		130		130		130		ns

(Notes, Caution, and Remarks are listed on the next page.)

**CSI mode serial transfer timing (master mode) (during communication at different potential)**  
**(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)**

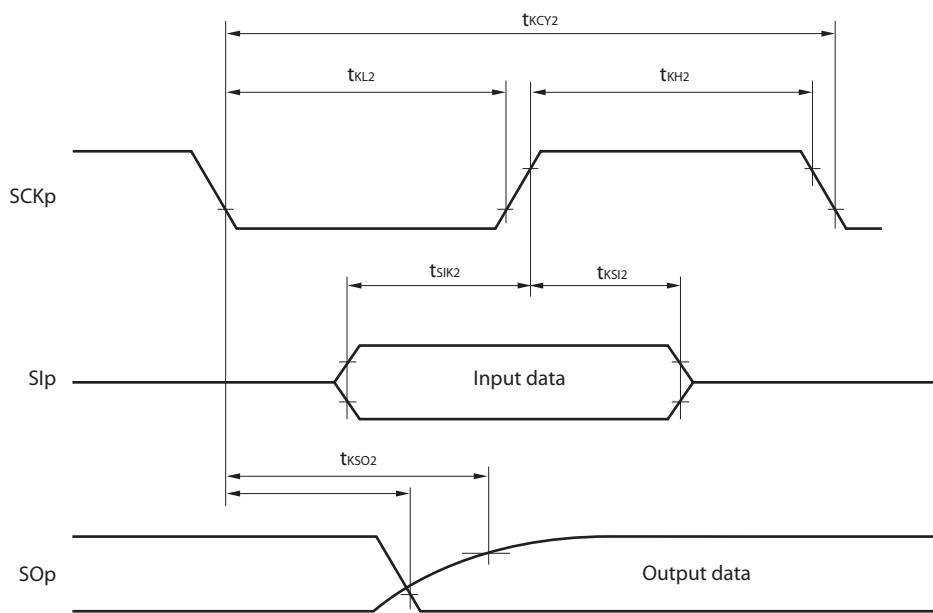


**CSI mode serial transfer timing (master mode) (during communication at different potential)**  
**(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)**

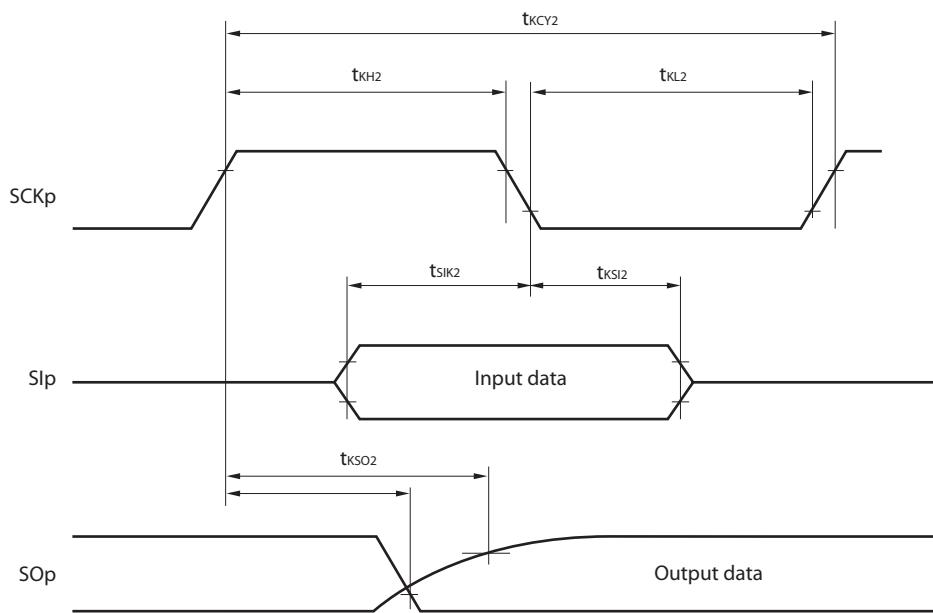


- Remarks**
1. p: CSI number ( $p = 00, 01, 10, 20, 30, 31$ ), m: Unit number, n: Channel number ( $mn = 00, 01, 02, 10, 12, 13$ ), g: PIM and POM number ( $g = 0, 1, 4, 5, 8, 14$ )
  2. CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential.  
Use other CSI for communication at different potential.

**CSI mode serial transfer timing (slave mode) (during communication at different potential)**  
**(When  $\text{DAP}_{mn} = 0$  and  $\text{CKP}_{mn} = 0$ , or  $\text{DAP}_{mn} = 1$  and  $\text{CKP}_{mn} = 1$ .)**



**CSI mode serial transfer timing (slave mode) (during communication at different potential)**  
**(When  $\text{DAP}_{mn} = 0$  and  $\text{CKP}_{mn} = 1$ , or  $\text{DAP}_{mn} = 1$  and  $\text{CKP}_{mn} = 0$ .)**



- Remarks**
1. p: CSI number ( $p = 00, 01, 10, 20, 30, 31$ ), m: Unit number,  
n: Channel number ( $mn = 00, 01, 02, 10, 12, 13$ ), g: PIM and POM number ( $g = 0, 1, 4, 5, 8, 14$ )
  2. CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential.  
Use other CSI for communication at different potential.

## 2.6 Analog Characteristics

### 2.6.1 A/D converter characteristics

Classification of A/D converter characteristics

Input channel	Reference Voltage		
	Reference voltage (+) = $\text{AV}_{\text{REFP}}$	Reference voltage (+) = $\text{V}_{\text{DD}}$	Reference voltage (+) = $\text{VBGR}$
Reference voltage (-) = $\text{AV}_{\text{REFM}}$	Reference voltage (-) = $\text{V}_{\text{SS}}$	Reference voltage (-) = $\text{AV}_{\text{REFM}}$	Reference voltage (-) = $\text{AV}_{\text{REFM}}$
ANI0 to ANI14	Refer to 2.6.1 (1).	Refer to 2.6.1 (3).	Refer to 2.6.1 (4).
ANI16 to ANI26	Refer to 2.6.1 (2).		
Internal reference voltage Temperature sensor output voltage	Refer to 2.6.1 (1).		–

**(1) When reference voltage (+) =  $\text{AV}_{\text{REFP}}$ /ANI0 (ADREFP1 = 0, ADREFP0 = 1), reference voltage (-) =  $\text{AV}_{\text{REFM}}$ /ANI1 (ADREFM = 1), target pin : ANI2 to ANI14, internal reference voltage, and temperature sensor output voltage**

( $T_A = -40$  to  $+85^\circ\text{C}$ ,  $1.6 \text{ V} \leq \text{AV}_{\text{REFP}} \leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$ ,  $\text{V}_{\text{SS}} = 0 \text{ V}$ , Reference voltage (+) =  $\text{AV}_{\text{REFP}}$ , Reference voltage (-) =  $\text{AV}_{\text{REFM}} = 0 \text{ V}$ )

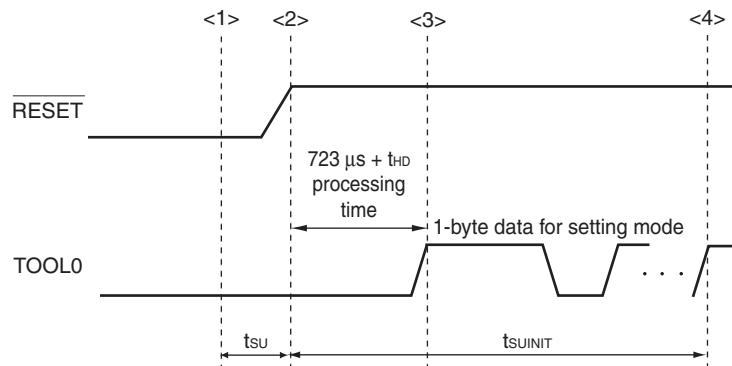
Parameter	Symbol	Conditions		MIN.	TYP.	MAX.	Unit
Resolution	RES			8		10	bit
Overall error <sup>Note 1</sup>	AINL	10-bit resolution $\text{AV}_{\text{REFP}} = \text{V}_{\text{DD}}$ <sup>Note 3</sup>	1.8 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$		1.2	$\pm 3.5$	LSB
			1.6 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$ <sup>Note 4</sup>		1.2	$\pm 7.0$	LSB
Conversion time	t <sub>CONV</sub>	10-bit resolution Target pin: ANI2 to ANI14	3.6 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$	2.125		39	$\mu\text{s}$
			2.7 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$	3.1875		39	$\mu\text{s}$
			1.8 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$	17		39	$\mu\text{s}$
			1.6 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$	57		95	$\mu\text{s}$
	t <sub>CONV</sub>	10-bit resolution Target pin: Internal reference voltage, and temperature sensor output voltage (HS (high-speed main) mode)	3.6 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$	2.375		39	$\mu\text{s}$
			2.7 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$	3.5625		39	$\mu\text{s}$
			2.4 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$	17		39	$\mu\text{s}$
Zero-scale error <sup>Notes 1, 2</sup>	E <sub>zs</sub>	10-bit resolution $\text{AV}_{\text{REFP}} = \text{V}_{\text{DD}}$ <sup>Note 3</sup>	1.8 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$			$\pm 0.25$	%FSR
			1.6 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$ <sup>Note 4</sup>			$\pm 0.50$	%FSR
Full-scale error <sup>Notes 1, 2</sup>	E <sub>fs</sub>	10-bit resolution $\text{AV}_{\text{REFP}} = \text{V}_{\text{DD}}$ <sup>Note 3</sup>	1.8 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$			$\pm 0.25$	%FSR
			1.6 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$ <sup>Note 4</sup>			$\pm 0.50$	%FSR
Integral linearity error <sup>Note 1</sup>	ILE	10-bit resolution $\text{AV}_{\text{REFP}} = \text{V}_{\text{DD}}$ <sup>Note 3</sup>	1.8 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$			$\pm 2.5$	LSB
			1.6 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$ <sup>Note 4</sup>			$\pm 5.0$	LSB
Differential linearity error <sup>Note 1</sup>	DLE	10-bit resolution $\text{AV}_{\text{REFP}} = \text{V}_{\text{DD}}$ <sup>Note 3</sup>	1.8 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$			$\pm 1.5$	LSB
			1.6 V $\leq \text{AV}_{\text{REFP}} \leq 5.5 \text{ V}$ <sup>Note 4</sup>			$\pm 2.0$	LSB
Analog input voltage	V <sub>AIN</sub>	ANI2 to ANI14		0		$\text{AV}_{\text{REFP}}$	V
		Internal reference voltage (2.4 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$ , HS (high-speed main) mode)			$\text{V}_{\text{BGR}}$ <sup>Note 5</sup>		V
		Temperature sensor output voltage (2.4 V $\leq \text{V}_{\text{DD}} \leq 5.5 \text{ V}$ , HS (high-speed main) mode)			$\text{V}_{\text{TMPS25}}$ <sup>Note 5</sup>		V

(Notes are listed on the next page.)

### 2.10 Timing of Entry to Flash Memory Programming Modes

( $T_A = -40$  to  $+85^\circ\text{C}$ ,  $1.8 \text{ V} \leq EV_{DD0} = EV_{DD1} \leq V_{DD} \leq 5.5 \text{ V}$ ,  $V_{SS} = EV_{SS0} = EV_{SS1} = 0 \text{ V}$ )

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Time to complete the communication for the initial setting after the external reset is released	$t_{SUINIT}$	POR and LVD reset must be released before the external reset is released.			100	ms
Time to release the external reset after the TOOL0 pin is set to the low level	$ts_u$	POR and LVD reset must be released before the external reset is released.	10			$\mu\text{s}$
Time to hold the TOOL0 pin at the low level after the external reset is released (excluding the processing time of the firmware to control the flash memory)	$t_{HD}$	POR and LVD reset must be released before the external reset is released.	1			ms



- <1> The low level is input to the TOOL0 pin.
- <2> The external reset is released (POR and LVD reset must be released before the external reset is released.).
- <3> The TOOL0 pin is set to the high level.
- <4> Setting of the flash memory programming mode by UART reception and complete the baud rate setting.

**Remark**  $t_{SUINIT}$ : Communication for the initial setting must be completed within 100 ms after the external reset is released during this period.

$ts_u$ : Time to release the external reset after the TOOL0 pin is set to the low level

$t_{HD}$ : Time to hold the TOOL0 pin at the low level after the external reset is released (excluding the processing time of the firmware to control the flash memory)

(TA = -40 to +105°C, 2.4 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V) (4/5)

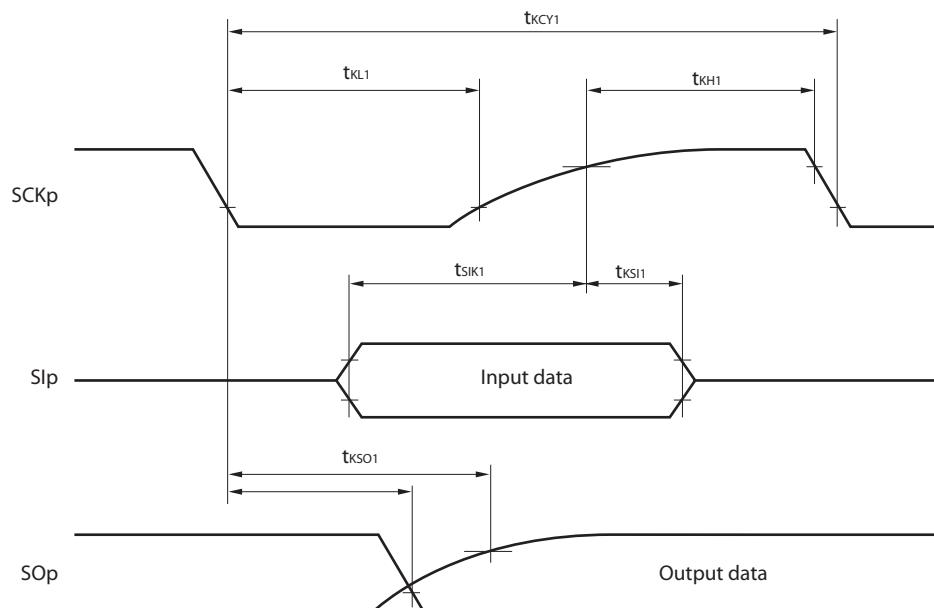
Items	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Output voltage, high	V <sub>OH1</sub>	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, I <sub>OH1</sub> = -3.0 mA	EV <sub>DD0</sub> – 0.7		V
			2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, I <sub>OH1</sub> = -2.0 mA	EV <sub>DD0</sub> – 0.6		V
			2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, I <sub>OH1</sub> = -1.5 mA	EV <sub>DD0</sub> – 0.5		V
	V <sub>OH2</sub>	P20 to P27, P150 to P156	2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V, I <sub>OH2</sub> = -100 μA	V <sub>DD</sub> – 0.5		V
Output voltage, low	V <sub>OL1</sub>	P00 to P07, P10 to P17, P30 to P37, P40 to P47, P50 to P57, P64 to P67, P70 to P77, P80 to P87, P90 to P97, P100 to P106, P110 to P117, P120, P125 to P127, P130, P140 to P147	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, I <sub>OL1</sub> = 8.5 mA		0.7	V
			4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, I <sub>OL1</sub> = 3.0 mA		0.6	V
			2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, I <sub>OL1</sub> = 1.5 mA		0.4	V
			2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, I <sub>OL1</sub> = 0.6 mA		0.4	V
	V <sub>OL2</sub>	P20 to P27, P150 to P156	2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V, I <sub>OL2</sub> = 400 μA		0.4	V
	V <sub>OL3</sub>	P60 to P63	4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, I <sub>OL3</sub> = 15.0 mA		2.0	V
			4.0 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, I <sub>OL3</sub> = 5.0 mA		0.4	V
			2.7 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, I <sub>OL3</sub> = 3.0 mA		0.4	V
			2.4 V ≤ EV <sub>DD0</sub> ≤ 5.5 V, I <sub>OL3</sub> = 2.0 mA		0.4	V

**Caution** P00, P02 to P04, P10 to P15, P17, P43 to P45, P50, P52 to P55, P71, P74, P80 to P82, P96, and P142 to P144 do not output high level in N-ch open-drain mode.

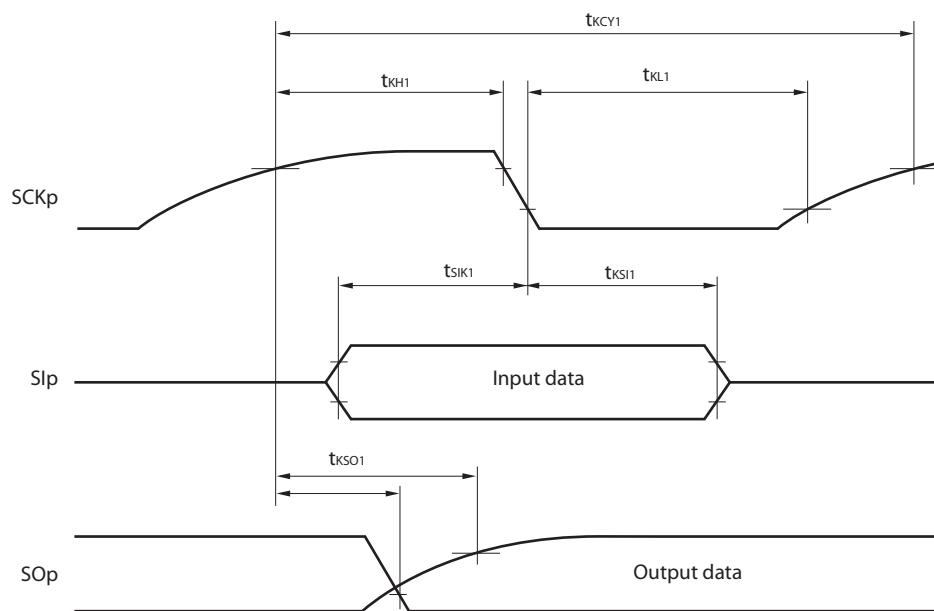
**Remark** Unless specified otherwise, the characteristics of alternate-function pins are the same as those of the port pins.

**CSI mode serial transfer timing (master mode) (during communication at different potential)**

(When DAPmn = 0 and CKPmn = 0, or DAPmn = 1 and CKPmn = 1.)

**CSI mode serial transfer timing (master mode) (during communication at different potential)**

(When DAPmn = 0 and CKPmn = 1, or DAPmn = 1 and CKPmn = 0.)



**Remarks** 1. p: CSI number ( $p = 00, 01, 10, 20, 30, 31$ ), m: Unit number ( $m = 00, 01, 02, 10, 12, 13$ ), n: Channel number ( $n = 0, 2$ ), g: PIM and POM number ( $g = 0, 1, 4, 5, 8, 14$ )

2. CSI01 of 48-, 52-, 64-pin products, and CSI11 and CSI21 cannot communicate at different potential. Use other CSI for communication at different potential.

### 3.8 Flash Memory Programming Characteristics

(TA = -40 to +105°C, 2.4 V ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
CPU/peripheral hardware clock frequency	f <sub>CLK</sub>	2.4 V ≤ V <sub>DD</sub> ≤ 5.5 V	1		32	MHz
Number of code flash rewrites <small>Notes 1,2,3</small>	C <sub>erwr</sub>	Retained for 20 years TA = 85°C <small>Note 4</small>	1,000			Times
		Retained for 1 years TA = 25°C		1,000,000		
		Retained for 5 years TA = 85°C <small>Note 4</small>	100,000			
		Retained for 20 years TA = 85°C <small>Note 4</small>	10,000			

- Notes**
- 1 erase + 1 write after the erase is regarded as 1 rewrite. The retaining years are until next rewrite after the rewrite.
  2. When using flash memory programmer and Renesas Electronics self programming library.
  3. These are the characteristics of the flash memory and the results obtained from reliability testing by Renesas Electronics Corporation.
  4. This temperature is the average value at which data are retained.

### 3.9 Dedicated Flash Memory Programmer Communication (UART)

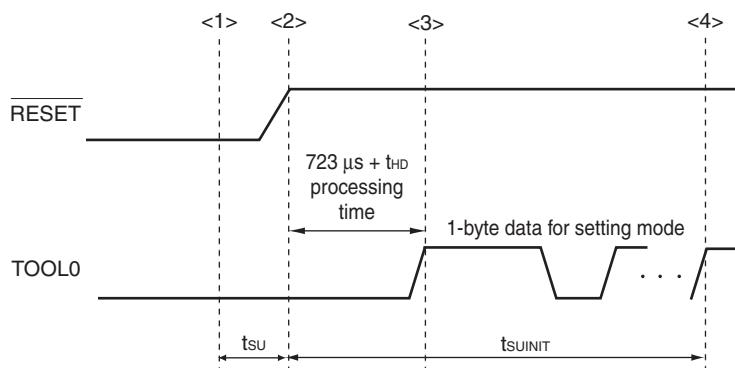
(TA = -40 to +105°C, 2.4 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Transfer rate		During serial programming	115,200		1,000,000	bps

### 3.10 Timing of Entry to Flash Memory Programming Modes

(TA = -40 to +105°C, 2.4 V ≤ EV<sub>DD0</sub> = EV<sub>DD1</sub> ≤ V<sub>DD</sub> ≤ 5.5 V, V<sub>SS</sub> = EV<sub>SS0</sub> = EV<sub>SS1</sub> = 0 V)

Parameter	Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Time to complete the communication for the initial setting after the external reset is released	t <sub>SUINIT</sub>	POR and LVD reset must be released before the external reset is released.			100	ms
Time to release the external reset after the TOOL0 pin is set to the low level	t <sub>SU</sub>	POR and LVD reset must be released before the external reset is released.	10			μs
Time to hold the TOOL0 pin at the low level after the external reset is released (excluding the processing time of the firmware to control the flash memory)	t <sub>HD</sub>	POR and LVD reset must be released before the external reset is released.	1			ms



- <1> The low level is input to the TOOL0 pin.
- <2> The external reset is released (POR and LVD reset must be released before the external reset is released.).
- <3> The TOOL0 pin is set to the high level.
- <4> Setting of the flash memory programming mode by UART reception and complete the baud rate setting.

**Remark** t<sub>SUINIT</sub>: Communication for the initial setting must be completed within 100 ms after the external reset is released during this period.

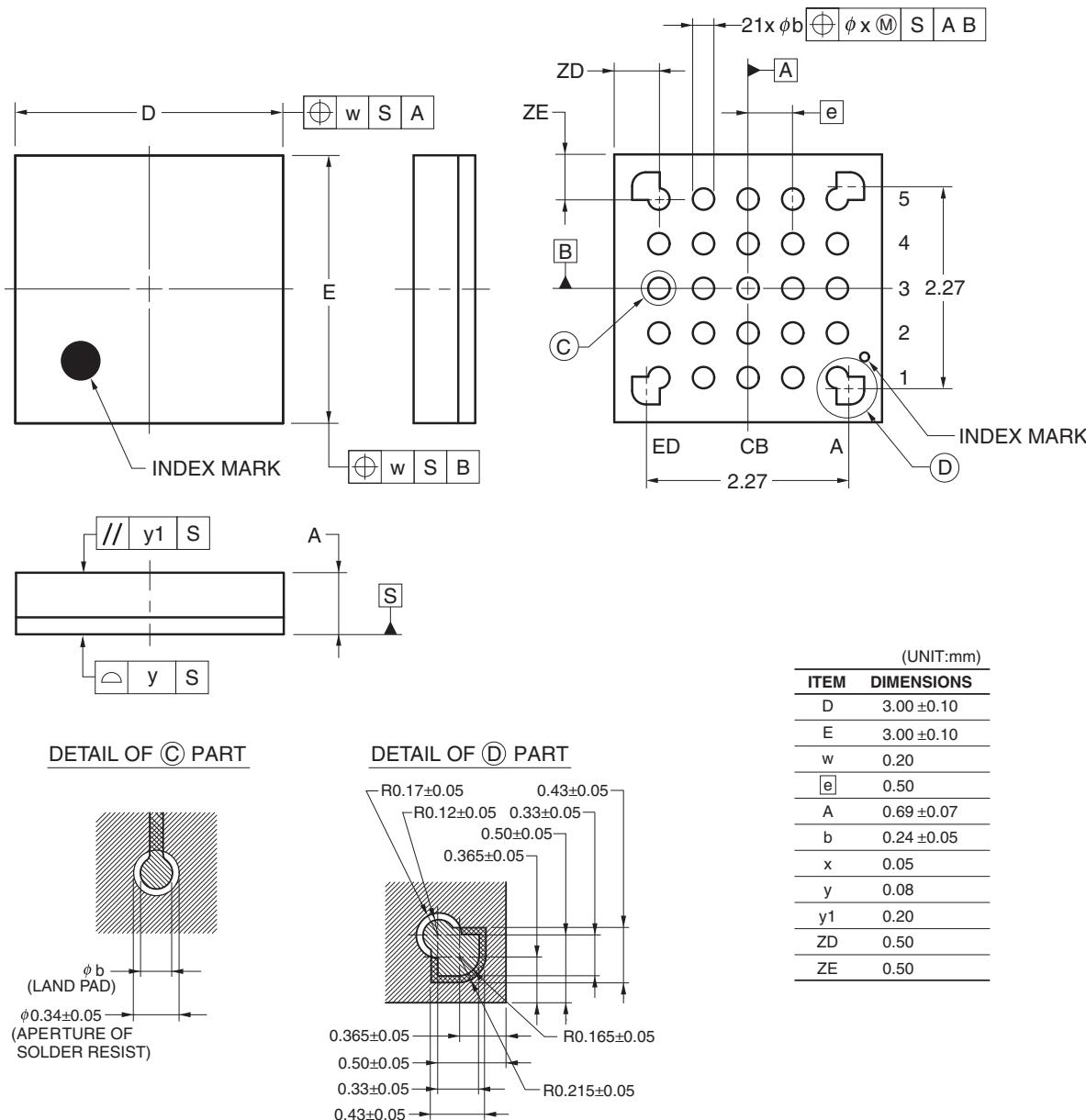
t<sub>SU</sub>: Time to release the external reset after the TOOL0 pin is set to the low level

t<sub>HD</sub>: Time to hold the TOOL0 pin at the low level after the external reset is released (excluding the processing time of the firmware to control the flash memory)

### 4.3 25-pin Products

R5F1008AALA, R5F1008CALA, R5F1008DALA, R5F1008EALA  
 R5F1018AALA, R5F1018CALA, R5F1018DALA, R5F1018EALA  
 R5F1008AGLA, R5F1008CGLA, R5F1008DGLA, R5F1008EGLA

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-WFLGA25-3x3-0.50	PWLG0025KA-A	P25FC-50-2N2-2	0.01

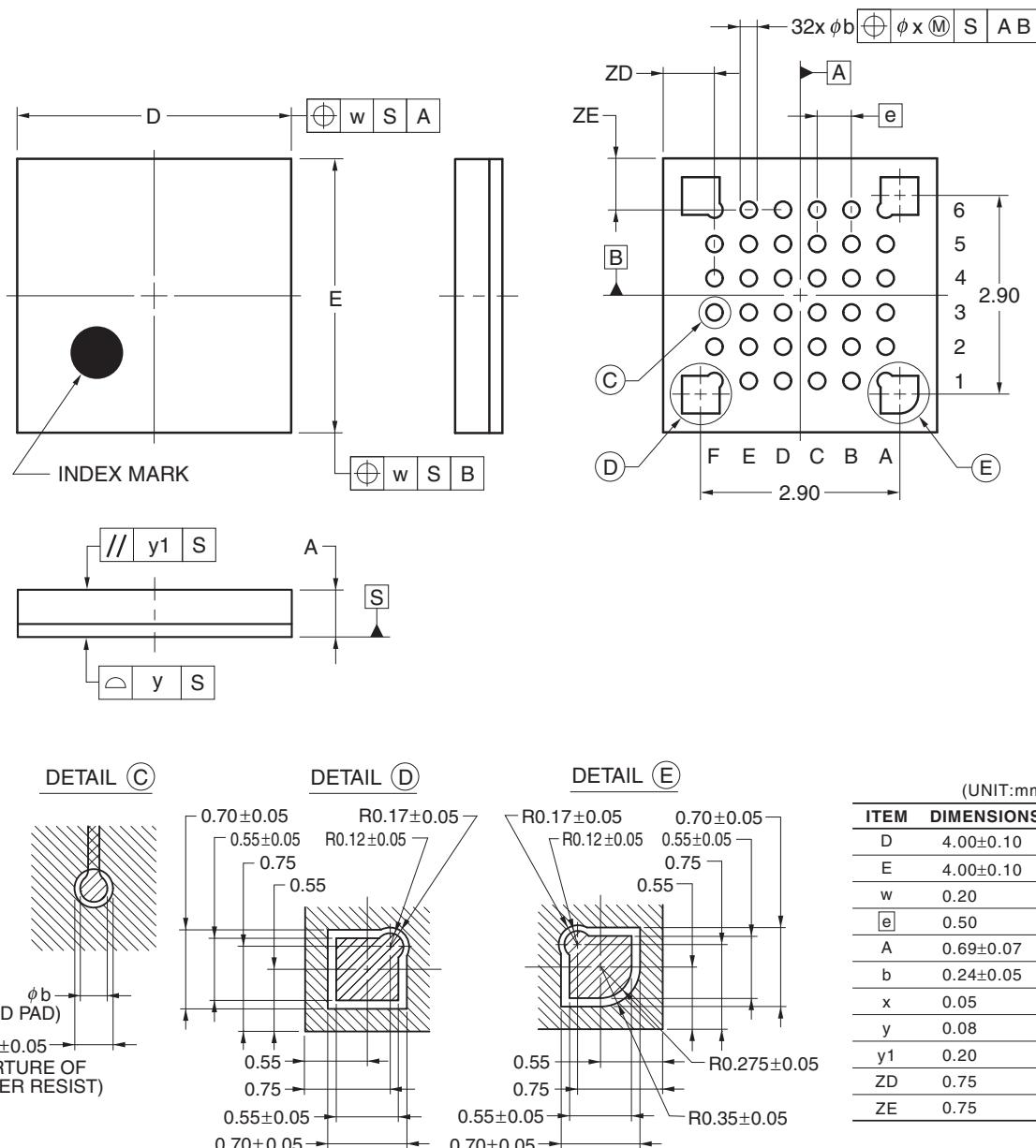


©2012 Renesas Electronics Corporation. All rights reserved.

## 4.6 36-pin Products

R5F100CAALA, R5F100CCALA, R5F100CDALA, R5F100CEALA, R5F100CFALA, R5F100CGALA  
 R5F101CAALA, R5F101CCALA, R5F101CDALA, R5F101CEALA, R5F101CFALA, R5F101CGALA  
 R5F100CAGLA, R5F100CCGLA, R5F100CDGLA, R5F100CEGLA, R5F100CFGGLA, R5F100CGGLA

JEITA Package Code	RENESAS Code	Previous Code	MASS (TYP.) [g]
P-WFLGA36-4x4-0.50	PWLG0036KA-A	P36FC-50-AA4-2	0.023



©2012 Renesas Electronics Corporation. All rights reserved.

Rev.	Date	Description	
		Page	Summary
3.00	Aug 02, 2013	118	Modification of table in 2.6.2 Temperature sensor/internal reference voltage characteristics
		118	Modification of table and note in 2.6.3 POR circuit characteristics
		119	Modification of table in 2.6.4 LVD circuit characteristics
		120	Modification of table of LVD Detection Voltage of Interrupt & Reset Mode
		120	Renamed to 2.6.5 Power supply voltage rising slope characteristics
		122	Modification of table, figure, and remark in 2.10 Timing Specs for Switching Flash Memory Programming Modes
		123	Modification of caution 1 and description
		124	Modification of table and remark 3 in Absolute Maximum Ratings ( $T_A = 25^\circ\text{C}$ )
		126	Modification of table, note, caution, and remark in 3.2.1 X1, XT1 oscillator characteristics
		126	Modification of table in 3.2.2 On-chip oscillator characteristics
		127	Modification of note 3 in 3.3.1 Pin characteristics (1/5)
		128	Modification of note 3 in 3.3.1 Pin characteristics (2/5)
		133	Modification of notes 1 and 4 in (1) Flash ROM: 16 to 64 KB of 20- to 64-pin products (1/2)
		135	Modification of notes 1, 5, and 6 in (1) Flash ROM: 16 to 64 KB of 20- to 64-pin products (2/2)
		137	Modification of notes 1 and 4 in (2) Flash ROM: 96 to 256 KB of 30- to 100-pin products (1/2)
		139	Modification of notes 1, 5, and 6 in (2) Flash ROM: 96 to 256 KB of 30- to 100-pin products (2/2)
		140	Modification of (3) Peripheral Functions (Common to all products)
		142	Modification of table in 3.4 AC Characteristics
		143	Addition of Minimum Instruction Execution Time during Main System Clock Operation
		143	Modification of figure of AC Timing Test Points
		143	Modification of figure of External System Clock Timing
		145	Modification of figure of AC Timing Test Points
		145	Modification of description, note 1, and caution in (1) During communication at same potential (UART mode)
		146	Modification of description in (2) During communication at same potential (CSI mode)
		147	Modification of description in (3) During communication at same potential (CSI mode)
		149	Modification of table, note 1, and caution in (4) During communication at same potential (simplified I <sup>2</sup> C mode)
		151	Modification of table, note 1, and caution in (5) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode) (1/2)
		152 to 154	Modification of table, notes 2 to 6, caution, and remarks 1 to 4 in (5) Communication at different potential (1.8 V, 2.5 V, 3 V) (UART mode) (2/2)
		155	Modification of table in (6) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (1/3)
		156	Modification of table and caution in (6) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (2/3)
		157, 158	Modification of table, caution, and remarks 3 and 4 in (6) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode) (3/3)
		160, 161	Modification of table and caution in (7) Communication at different potential (1.8 V, 2.5 V, 3 V) (CSI mode)